

**DECLARATION AND POWER OF
ATTORNEY FOR UTILITY PATENT APPLICATION**

| | | | | |
|--|--------------------------|--------------------------------------|-----------------------------|----------------------------|
| As a below named inventor, I hereby declare that: | | | | |
| My residence, post office address, and citizenship are as stated below next to my name. | | | | |
| I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled " SOI MOSFET JUNCTION DEGRADATION USING MULTIPLE BURIED AMORPHOUS LAYERS " the specification of which: | | | | |
| <input checked="" type="checkbox"/> | is attached hereto OR | | | |
| | was filed on | (MM/DD/YY) | and assigned serial. no. | |
| | and was amended on | | (MM/DD/YY) (if applicable) | |
| I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment specifically referred to above. | | | | |
| I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56. | | | | |
| I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or 365(b) of any foreign application(s) for patent or inventor's certificate, or 365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below any foreign application for patent or inventor's certificate, or any PCT international application having a filing date before that of the application on which priority is claimed. | | | | |
| Prior Foreign Application Number(s) | Country | Foreign Filing Date (MM/DD/YY) | Priority Not Claimed | Certified Copy Attached |
| I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below. | | | | |
| Application Number(s) | | Filing Date (MM/DD/YY) | | |
| | | | | |

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or 365(c) of any PCT international application designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose all information known to me to be material to patentability of the subject matter claimed in this application, as "materiality" is defined in 37 U.S.C. § 1.56, which becomes available between the filing date of the prior application and the national or PCT international filing date of this application:

| Application Numbers(s) | Filing Date (MM/DD/YY) |
|------------------------|------------------------|
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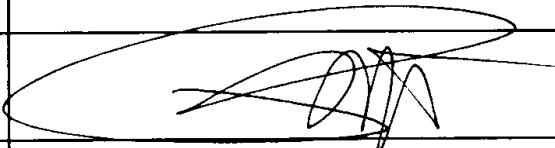
I hereby revoke any previous Power of Attorney and appoint:

Elizabeth A. Apperley, Reg. No. 36,428; Bradley Botsch, Reg. No. 34,552; Michael Caywood, Reg. No. 37,797; Daniel R. Collopy, Reg. No. 33,667; Paul S. Drake, Reg. No. 33,491; Rajendra Jaipershad, Reg. No. 44,168; Diana Roberts, Reg. No. 36,654; Richard J. Roddy, Reg. No. 27,688; Harry A. Wolin, Reg. No. 32,638; and Timothy M. Honeycutt, Reg. No. 37,153

as my attorneys with full power of substitution and revocation, to prosecute the application, to make alterations and amendments therein, to transact all business in the Patent and Trademark Office in connection therewith, to receive any Letters Patent, and for one year after issuance of such Letters Patent to file any request for a certificate of correction that may be deemed appropriate.

I hereby direct that all correspondence and telephone calls be addressed to Timothy M. Honeycutt, Attorney at Law, P.O. Box 1577, Cypress, Texas 77410-1577, (281) 379-7999, attorney for the prospective assignee of this application.

I hereby declare that all statements made of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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|---|--|-----------------|
| Name of Sole or First Inventor | Andy Wei | |
| Inventor's Signature |  | Date 2/20/02 |
| Residence Address | 9323 Manchaca Rd. #125, Austin, TX 78748 | |
| Post Office Address (If different from residence address) | N/A | |
| Citizenship | U.S. | |

| | | |
|---|---|------|
| Name of Joint Inventor | Akif Sultan | |
| Inventor's Signature | | Date |
| Residence Address | 7117 Wood Hollow Dr. #321, Austin, TX 78731 | |
| Post Office Address (If different from residence address) | N/A | |
| Citizenship | India | |
| Name of Joint Inventor | David Wu | |
| Inventor's Signature | | Date |
| Residence Address | 10222 Dianella Ln., Austin, TX 78759 | |
| Post Office Address (If different from residence address) | N/A | |
| Citizenship | U.S. | |

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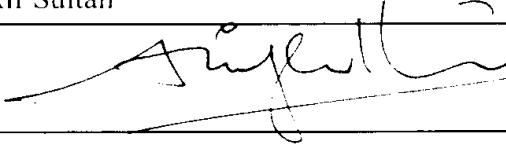
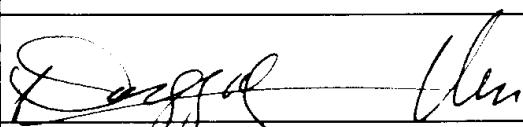
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| Name of Sole or First Inventor | Andy Wei | |
| Inventor's Signature | | Date |
| Residence Address | 9323 Manchaca Rd. #125, Austin, TX 78748 | |
| Post Office Address (If different from residence address) | N/A | |
| Citizenship | U.S. | |

| | | |
|---|--|-----------------|
| Name of Joint Inventor | Akif Sultan | |
| Inventor's Signature |  | Date 2/27/02 |
| Residence Address | 7117 Wood Hollow Dr. #321, Austin, TX 78731 | |
| Post Office Address (If different from residence address) | N/A | |
| Citizenship | India | |
| Name of Joint Inventor | David Wu | |
| Inventor's Signature |  | Date 2/27/02 |
| Residence Address | 10222 Dianella Ln., Austin, TX 78759 | |
| Post Office Address (If different from residence address) | N/A | |
| Citizenship | U.S. | |